

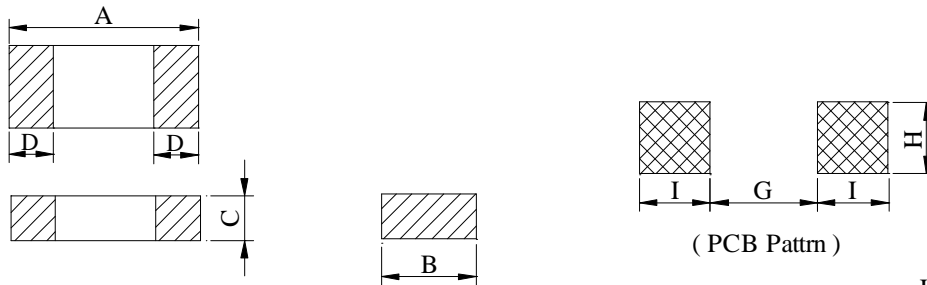
SPECIFICATION FOR APPROVAL

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	SM□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



Unit : m/m

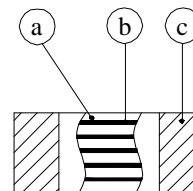
Series	A	B	C	D	G	H	I
SM4532	4.5±0.2	3.2±0.2	1.5±0.2	0.60±0.4	3.0	3.0	1.5
SM4516	4.5±0.2	1.6±0.2	1.6±0.2	0.60±0.4	3.0	1.4	1.5
SM3266	3.2±0.2	1.6±0.2	1.6±0.2	0.60±0.4	2.2	1.4	1.1
SM3261	3.2±0.2	1.6±0.2	1.1±0.2	0.60±0.4	2.2	1.4	1.1
SM2029	2.0±0.2	1.2±0.2	0.9±0.2	0.50±0.3	1.0	1.0	1.0
SM1608	1.6±0.2	0.8±0.2	0.8±0.2	0.30±0.2	0.7	0.7	0.7

II . SCHEMATIC DIAGRAM :



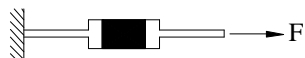
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

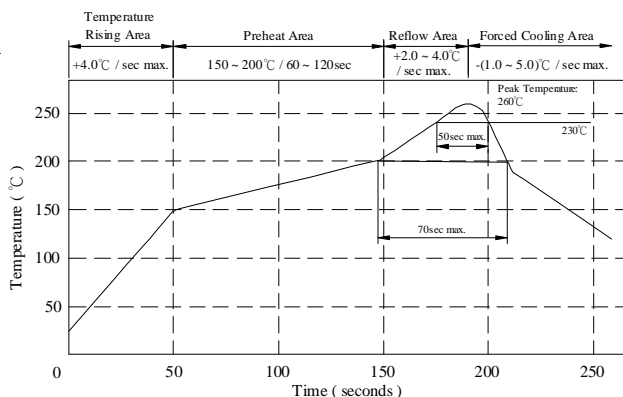
- a . Storage temp. : -40°C ---- +105°C
- b . Operating temp. : -55°C ---- +125°C
- c . Terminal Strength :



Type	F (kgf)	time (sec)
SM4532	1.5	30±5
SM4516	1.0	
SM3261	1.0	
SM3266	1.0	
SM2029	0.6	
SM1608	0.5	

- d . Solderability : Preheat : 150~25°C for 60 seconds
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
 Solder temp. : 260±5°C
 Flux : Rosin
 Dip time : 4±1 seconds

Peak Temp : 260°C max.
 Max time above 230°C : 50sec max.
 Max time above 200°C : 70sec max.



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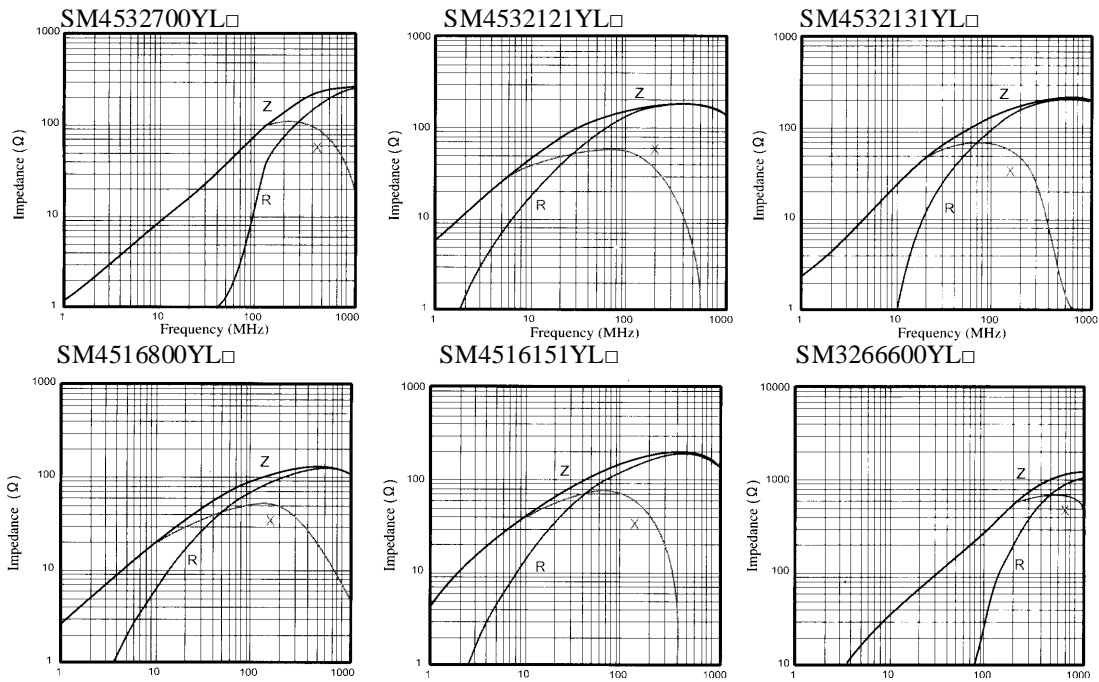
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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	SM□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
SM4532700YL□-□□□	70±25%	0.3	300
SM4532121YL□-□□□	120±25%	0.3	300
SM4532131YL□-□□□	125±25%	0.3	300
SM4516800YL□-□□□	80±25%	0.3	300
SM4516151YL□-□□□	150±25%	0.3	300
SM3266600YL□-□□□	60±25%	0.3	400

- 1). □ : Packaging Information... A : Bulk B : Taping Reel
 2). "- □□□ " : Reference code



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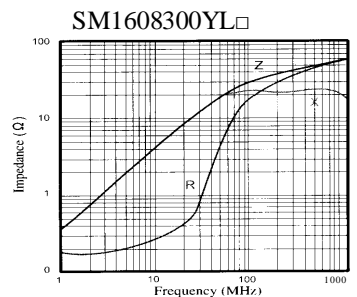
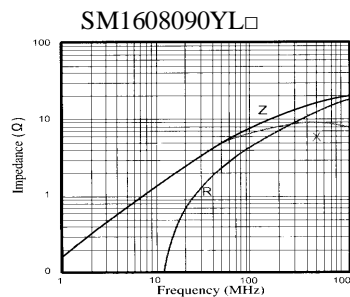
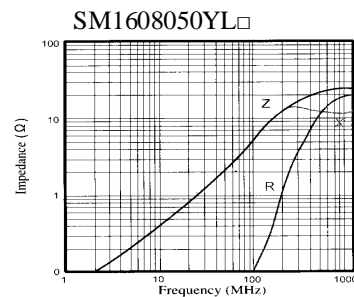
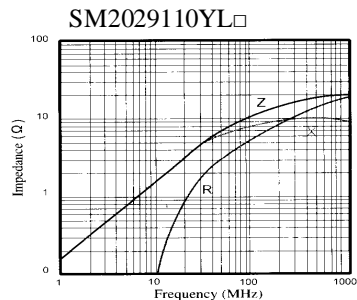
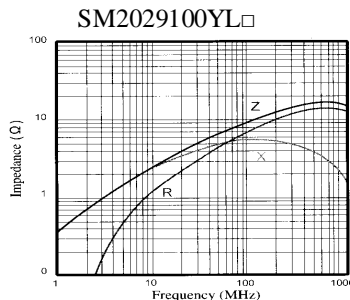
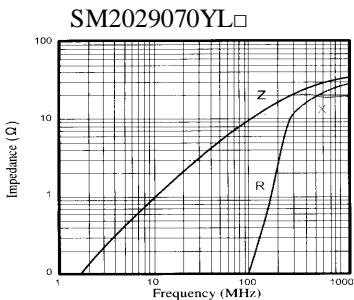
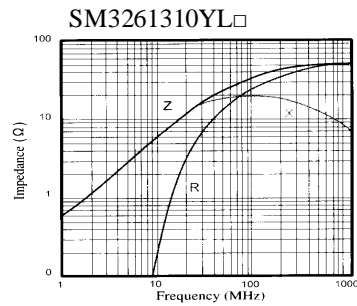
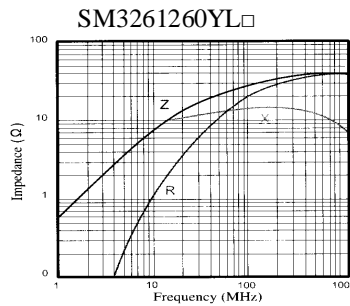
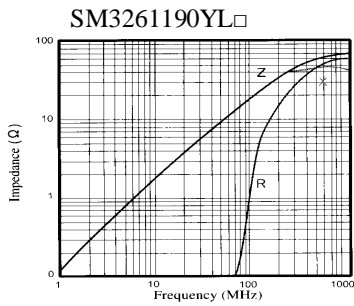
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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO. ABC'S ITEM NO.	SM□□□□□□□□L□-□□□
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V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance (Ω) at 100MHz	RDC (Ω) max.	IDC (mA) max.
SM3261190YL□-□□□	19±25%	0.2	500
SM3261260YL□-□□□	26±25%	0.2	500
SM3261310YL□-□□□	31±25%	0.2	500
SM2029070YL□-□□□	7±25%	0.2	600
SM2029100YL□-□□□	10±25%	0.2	600
SM2029110YL□-□□□	11±25%	0.2	600
SM1608050YL□-□□□	5±25%	0.2	600
SM1608090YL□-□□□	9±25%	0.2	500
SM1608300YL□-□□□	30±25%	0.3	400

- 1). □ : Packaging Information... [A] : Bulk [B] : Taping Reel
 2). "- □□□ " : Reference code



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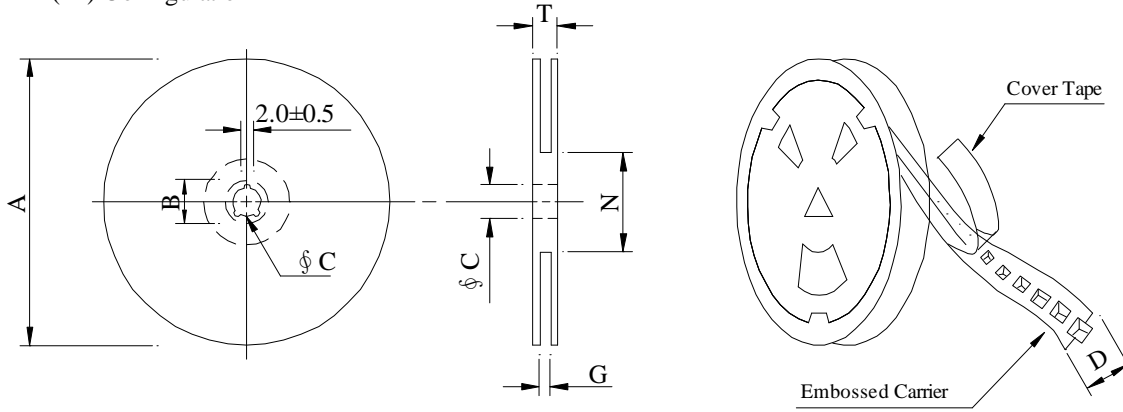
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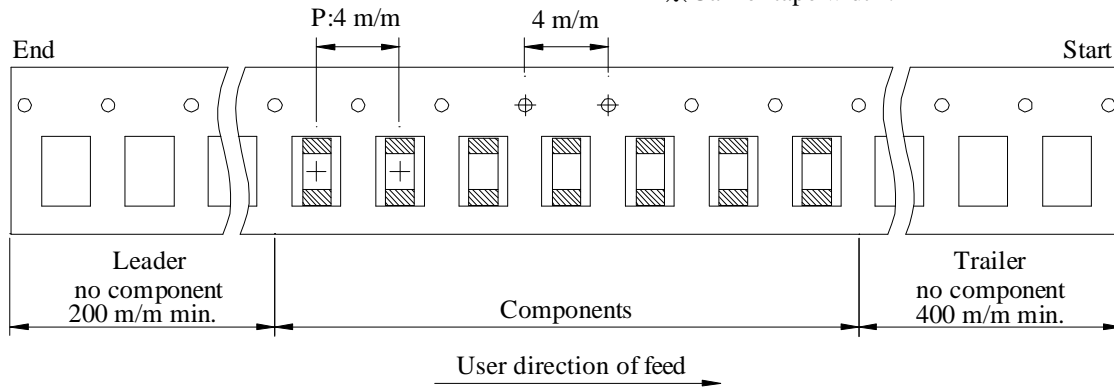
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VI . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5
07 - 12	178	21±0.8	13	12	14 ⁺⁰	50 ⁻⁰	16.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (kpcs)	G.W. (Kg)	Size (cm)
SM1608	4,000	90	07 - 08	200	7.0	41 x 39 x 22
SM2029	4,000	120	07 - 08	200	8.5	41 x 39 x 22
SM3261	3,000	150	07 - 08	120	8.5	41 x 39 x 22
SM3266	2,000	140	07 - 08	80	8.2	41 x 39 x 22
SM4516	2,000	180	07 - 12	80	9.7	41 x 39 x 22
SM4532	1,000	170	07 - 12	30	9.3	41 x 39 x 22

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		ABC'S ITEM NO.	

(4) TYPE DIMENSIONS

Fig 1.

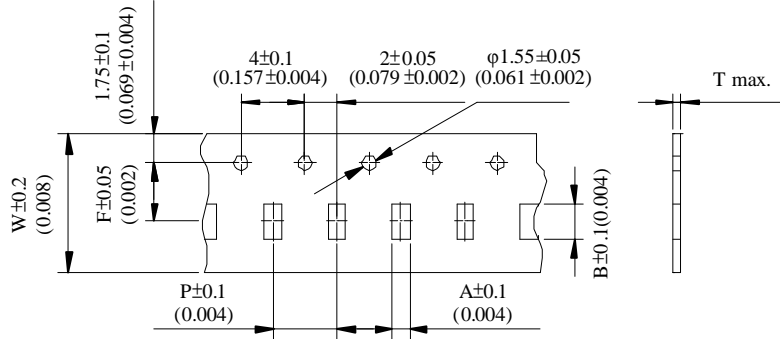
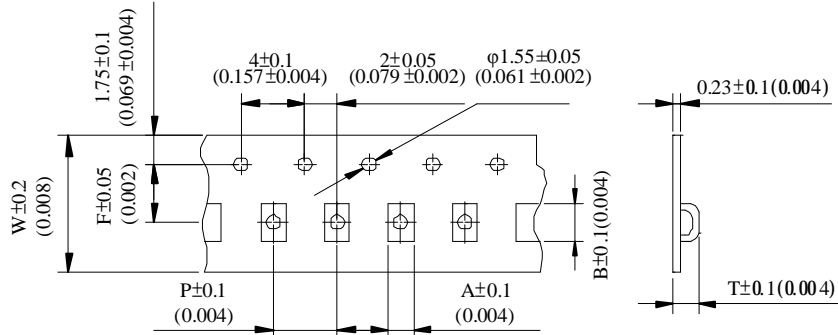


Fig 2.



Unit:m/m

Type	A	B	F	P	T	W	Fig
SM1608	1.05	1.85	3.50	4.0	1.10	8.0	1
SM2029	1.50	2.30	3.50	4.0	1.10	8.0	1
SM3261	1.88	3.50	3.50	4.0	1.27	8.0	2
SM3266	1.88	3.53	3.50	4.0	1.80	8.0	2
SM4516	1.93	4.95	5.50	4.0	1.93	12.0	2
SM4532	3.66	4.95	5.50	8.0	1.85	12.0	2

